List of Competencies for On-the-Job Training (OJT) Work-Study Diploma in Microelectronics (Process)

Applicants applying for this course must be free from colour appreciation deficiency. A score of 100% from the **Colour Blindness Test** is mandatory for course admission.

S/N	List of Competencies (Standard)	Company to indicate '√' for OJT competencies it can provide						
Perform semiconductor manufacturing protocol								
1	Execute safe work practices							
2	Executive risk control measures							
3	Execute good manufacturing practices							
Perfo	rm semiconductor manufacturing technology							
4	Execute semiconductor manufacturing processes							
5	Measure process parameter with metrology technique							
6	Optimise semiconductor manufacturing processes							
Imple	ment New Product Integration and Introduction (NPI)							
7	Analyse key process parameters							
8	Determine upper and lower process control window							
9	Evaluate process window							
Apply	Quality Engineering process							
10	Analyse defect density information in the manufacturing process							
11	Analyse out-of-control and abnormal chart trends							
12	Perform failure analysis							
Revie	w quality improvement with Data Analytics							
13	Apply quality management tools for continuous process improvement							
14	Analyse manufacturing performance							
15	Recommend parameters for manufacturing enhancement							
Imple	ment automation system							
16	Carry out automation system operations							
17	Operate MES (manufacturing execution system)							
18	Control APC (advance process control) system							
Imple	ment IoT system							
19	Integrate devices in IoT system							
20	Perform operational checks on application program for IoT system							

	S/N	List of Competencies (Standard)	Company to indicate '√' for OJT competencies it can provide					
	21	Verify IoT system performance with test result						
C)evel	op project management plan						
	22	Conduct project planning						
	23	Produce technical reports						
	24	Conduct technical presentation						
		Sub-total of Competencies (Standard)						
L	ist o	f Competencies (Company-specific)						
	1							
	2							
	3							
	4							
	5							
	6		1					
	te:	Sub-total of Competencies (Company-specific)						
i)))	If con whic [i.e. 5	pany must be able to provide OJT for at least 75% of the Least mpany is unable to meet the 75%, please propose alternate hare unique to company operations. Alternate competencies of the list of competencies (standard) + 25% alternate competernate competencies (Company-specific) must be reviewed.	e course-related compet es are capped at 25%. etencies (Company-specific					
d)	Trair	Trainees must receive OJT and be assessed for All competencies selected in this List.						
-ot	al no	of competencies selected by company for OJT						
Γot	al no	. of competencies listed (standard & company specific)						
Pe	rcenta	age of selected competencies						
Со	mple	ted By:						
	me	Compan	v					

MODULE SYPNOSIS – WSDip in Microelectronics (Process)

Course Objective

This course is your gateway to an exciting career in the manufacturing sector. You will learn essential skills to improve processes and make production more efficient. By analysing trend charts and identifying issues, you will play a vital role in ensuring everything runs smoothly. As you progress through the course, you will build the knowledge needed to tackle real-world challenges in manufacturing. You will become confident in spotting problems and suggesting improvements.

Modules Synopsis

Perform Semiconductor Manufacturing Protocol

On completion of the module, trainees should be able to identify workplace hazard and apply proper usage of the personal protective equipment (PPE). They should also be able to execute good manufacturing practices.

Semiconductor Technology

On completion of the module, trainees should be able to perform semiconductor manufacturing process and apply metrology methodology for semiconductor manufacturing.

Data Analytics for Quality Improvement

On completion of the module, trainees should be able to apply data analytic skills for semiconductor manufacturing.

Computer Programming & IoT Integration

On completion of the module, trainees should be able to write application program to integrate IoT devices into system using programming concept and language.

Project Management & Technical Writing

On completion of the module, trainees should be able to plan, execute and monitor manufacturing process to meet project scope, schedule and cost requirements; as well as write and present technical report, apply communication and supervision skills to build essential relationships at the workplace.

Company Project

On completion of this module, trainees should be able to plan, supervise and execute microelectronics equipment-related projects for manufacturing process improvement.

Process Integration

On completion of the module, trainees should be able to understand basic semiconductor process integration and analyze data to improve yield and performance.

Quality Engineering

On completion of the module, trainees should be able to analyse defect density, perform capability analysis and monitor abnormal control charts trends in manufacturing process.

Process Automation

On completion of the module, trainees should be able to apply robotic system and electromechanical control systems which includes common input/output devices, pneumatics, electropneumatics systems and PLC in process control system.

MODULE SYPNOSIS – WSDip in Microelectronics (Process)

On-the-Job Training

On completion of the module, trainees should be able to apply the skills and knowledge acquired at ITE College and workplace to take on the full job scope, including supervisory function, where appropriate, at the company.

TRAINING PATTERN SCHEDULE

WSDip in Microelectronics (Process)

Day Release - Trainees attend 1 to 2 days of lessons per week at ITE, with the remaining work-week spent at the workplace for On-the-Job Training.

April'26 Intake	April – June 2026		July – September 2026		October – December 2026		January – March 2027		
1 st Year Off-JT @ ITE	2 days/week	ITE Vacation (June) 4 weeks	2 days/week	ITE Vacation (Sept) 2 weeks	2 days/week	ITE Vacation (Dec) 4 weeks	2 days/week	ITE Vacation (March) 2 weeks	
April'26 Intake	April – June 2027		July – September 2027		October – December 2027		January – March 2028		
2 nd Year Off-JT @ ITE	2 days/week	ITE Vacation (June) 4 weeks	2 days/week	ITE Vacation (Sept) 2 weeks	1 day/week	ITE Vacation (Dec) 4 weeks	1 day/week	ITE Vacation (March) 2 weeks	
April'26 Intake	April'26 Intake April – June 2028 July – September 2028								
3 rd Year Off-JT @ ITE	2 days/week	ITE Vacation (June) 4 weeks	2 days/week	ITE Vacation (Sept) 2 weeks	WSDip Programme 2026 Start: 1 April 2026 End: 30 September 2028 Duration: 2.5 years Final results release may be later than programme end date				